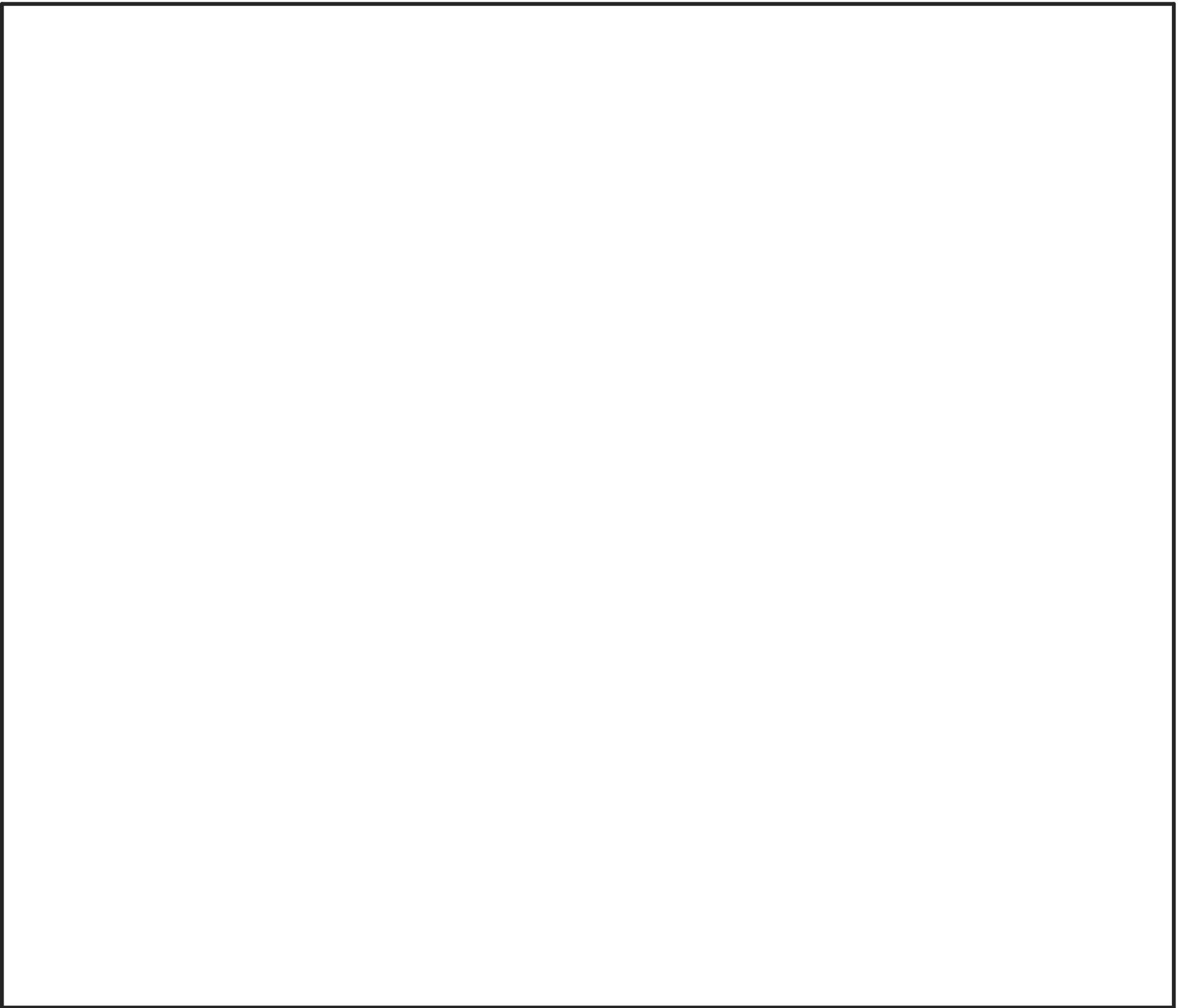
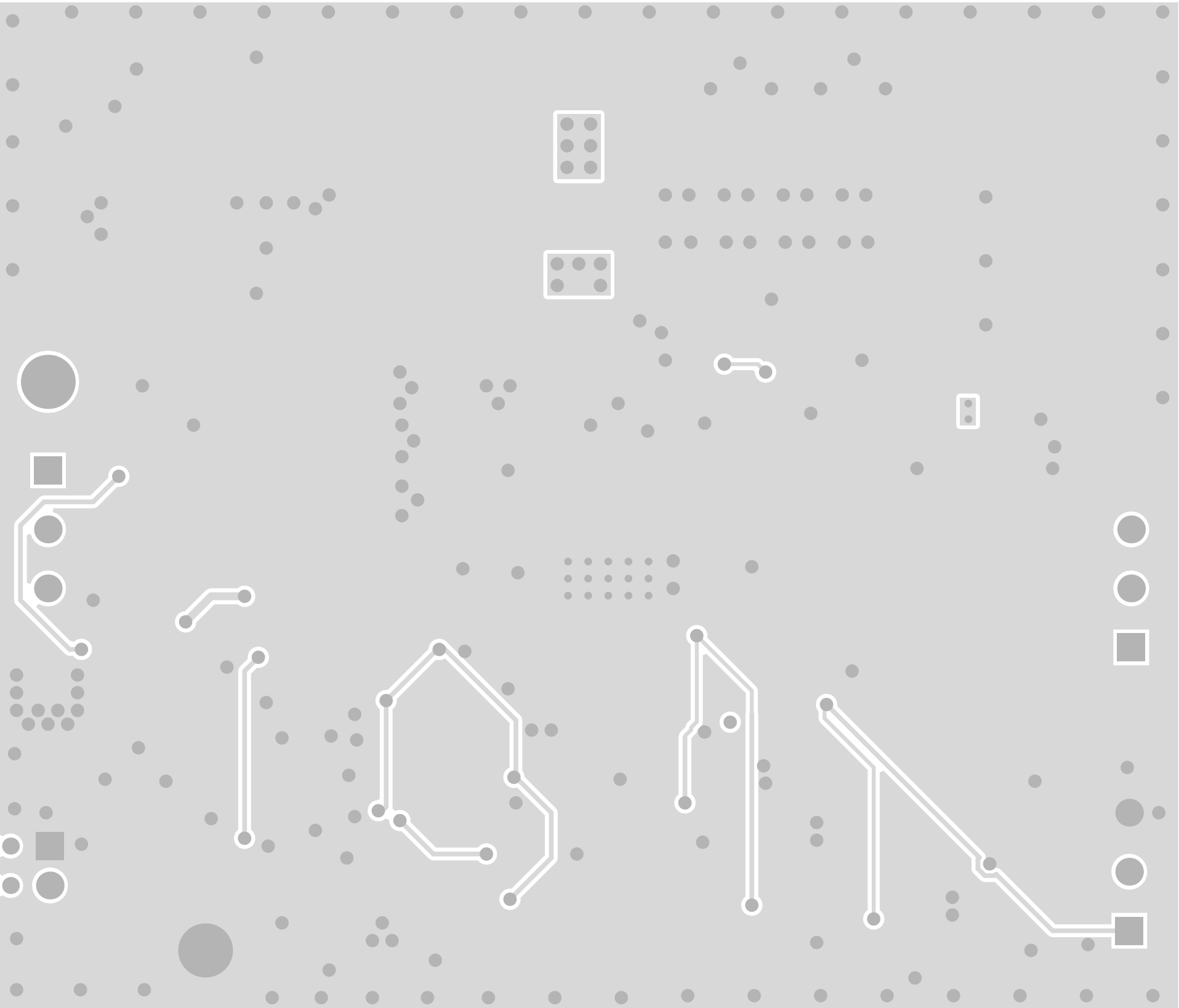


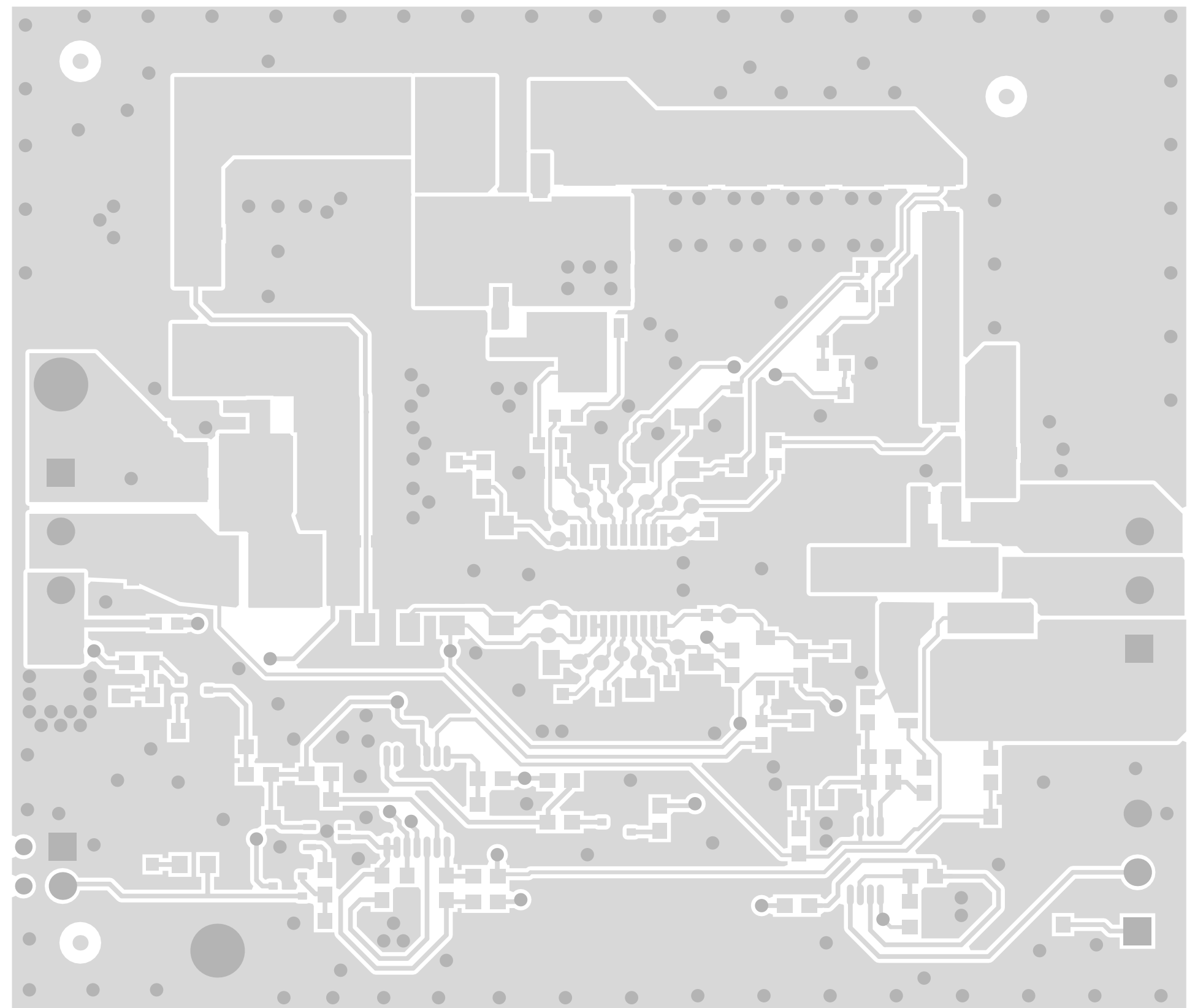
M2 Board Dimensions



M1 Board Outline



Bottom Layer



Top Layer

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